

On page 11, line 16, after "layer" please delete "24" and insert --26--;

On page 11, line 23, after "A" please delete "course" and insert --coarse--;

On page 12, line 3, after "further" please delete "provides" and insert --provide--;

On page 12, line 24, after "28" please insert --and polyimide layer 26--.

IN THE CLAIMS

Please amend the claims as follows:

- 1 1. (Amended) A method for manufacturing a plurality of thinned integrated
- 2 circuits from a semiconductor wafer having a thickness, a front surface and a backside
- 3 surface, comprising:
- 4 defining a plurality of grooves into said front surface of said semiconductor wafer
- 5 to define said plurality of dies, said grooves penetrating into said surface at a
- 6 predetermined distance less than said thickness of said semiconductor wafer so that
- 7 said plurality of dies remain integral with said wafer;
- 8 mounting said wafer to a flat rigid substrate to support said wafer, said wafer
- 9 being mounted to said substrate with said front surface turned toward said substrate;
- 10 mechanically removing a predetermined portion of said backside of said wafer
- 11 until said thickness of said wafer is reduced to expose said plurality of grooves to said
- 12 backside in preparation to separating said plurality of said dies, said dies remaining [of]
- 13 mounted to said substrate; and
- 14 releasing said plurality of dies from said substrate.